

TECHNICAL REPORT



Thermal standardization on semiconductor packages – Part 1: Thermal resistance and thermal parameter of BGA, QFP type semiconductor packages

INTERNATIONAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

THERMAL STANDARDIZATION ON SEMICONDUCTOR PACKAGES –**Part 1: Thermal resistance and thermal parameter of BGA,
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A list of all parts in the IEC 63378 series, published under the general title *Thermal standardization on semiconductor packages*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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THERMAL STANDARDIZATION ON SEMICONDUCTOR PACKAGES –

Part 1: Thermal resistance and thermal parameter of BGA, QFP type semiconductor packages

1 Scope

This part of IEC 63378 specifies the terms and definitions that are commonly used for thermal characteristics of BGA and QFP type semiconductor packages, and guidelines to use these thermal characteristics.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-4, *Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor device packages*